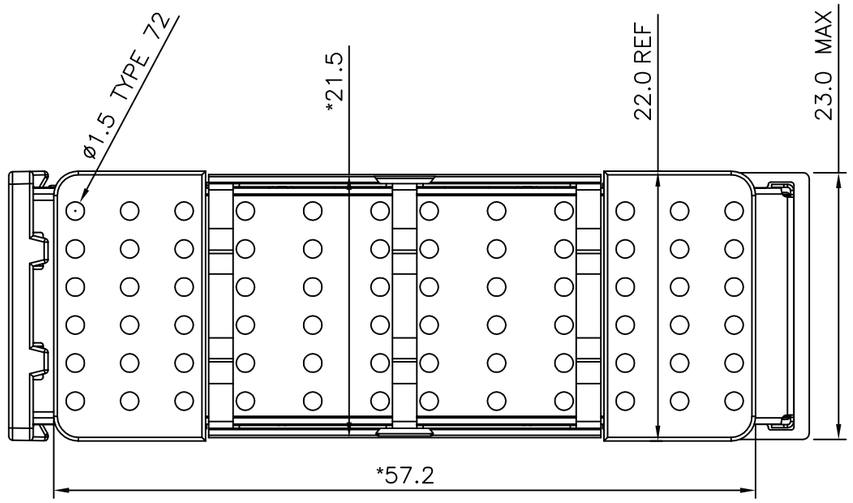
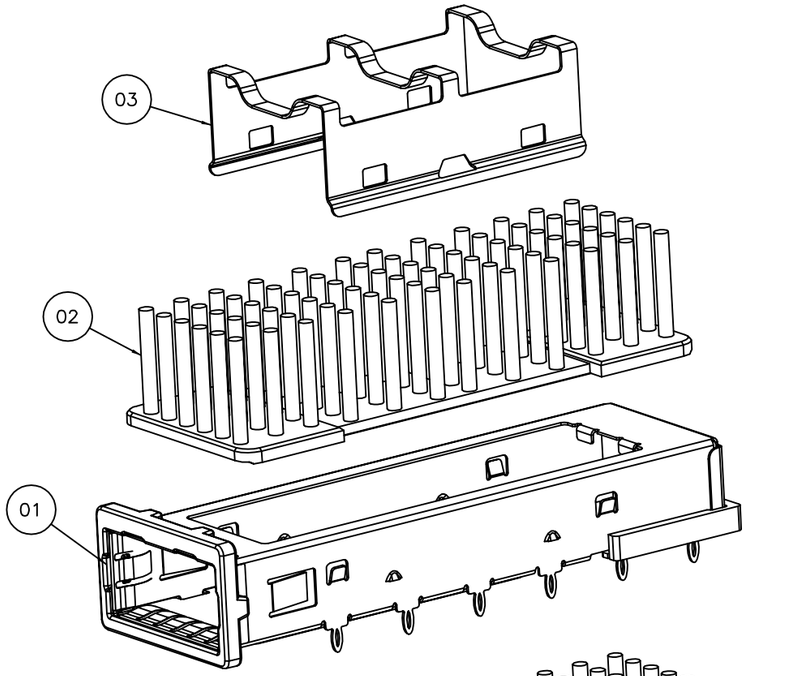
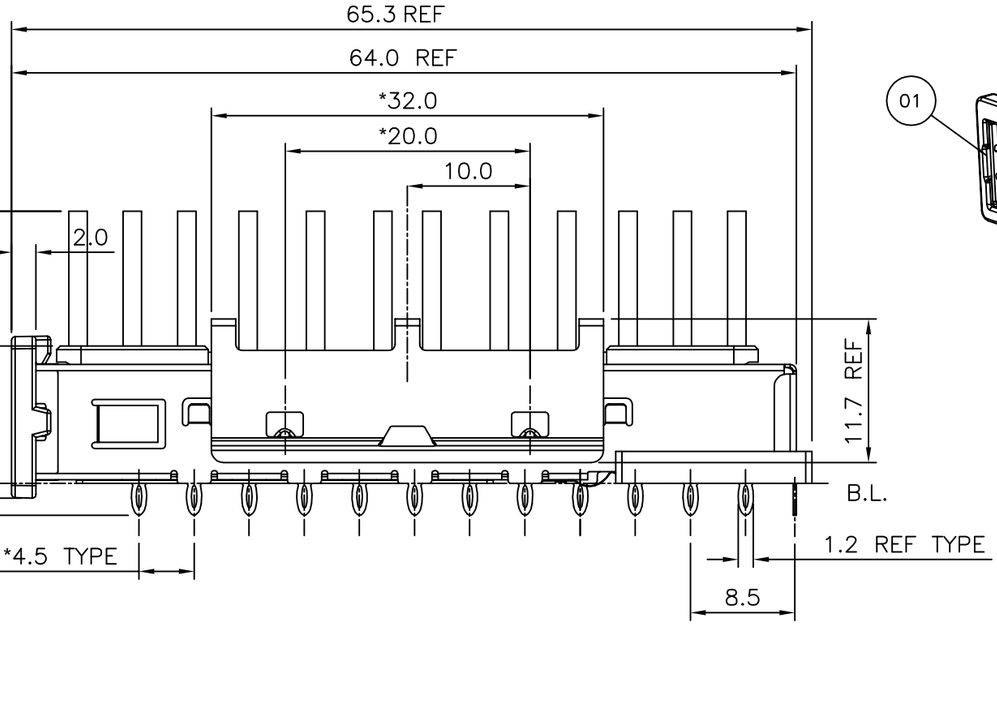
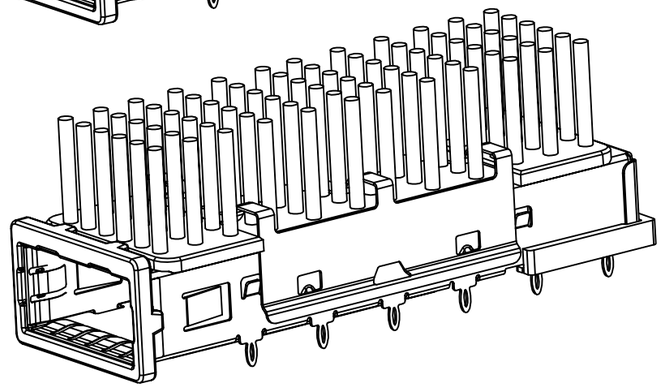
A1RFRD10

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD









PART NUMBER: XFP003-L

No.	DESCRIPATION	Q'ty	MATERIAL	PLATING	REMARK
01	XFP CAGE ASSEMBLY (Non-Logo)	1			
02	XFP HEAT SINK (**11.00**mm)	1	AL	Ni	
03	XFP HEAT SINK CLIP	1	SUS		

DETACHED LISTS

MM (INCH)

TOLERANCES EXCEPT AS NOTED

MM
.0 ± 0.2 ±
.00 ± 0.15 ±
.000 ± 0.075 ±

ANGLES ± 0.5

THIRD ANGLE PROJECTION

DFTO tzou	DATE 06/02/06'	
CHKD	DATE	
MFO	DATE	
APPVL	DATE	
MATERIAL :		
QT'Y :		
FINISH :		
SCALE : 1 : 2		

FULL RISE ELECTRONIC CO., LTD

TITLE (Non-Logo)

XFP CAGE WITH PCI HEAT SINK KIT

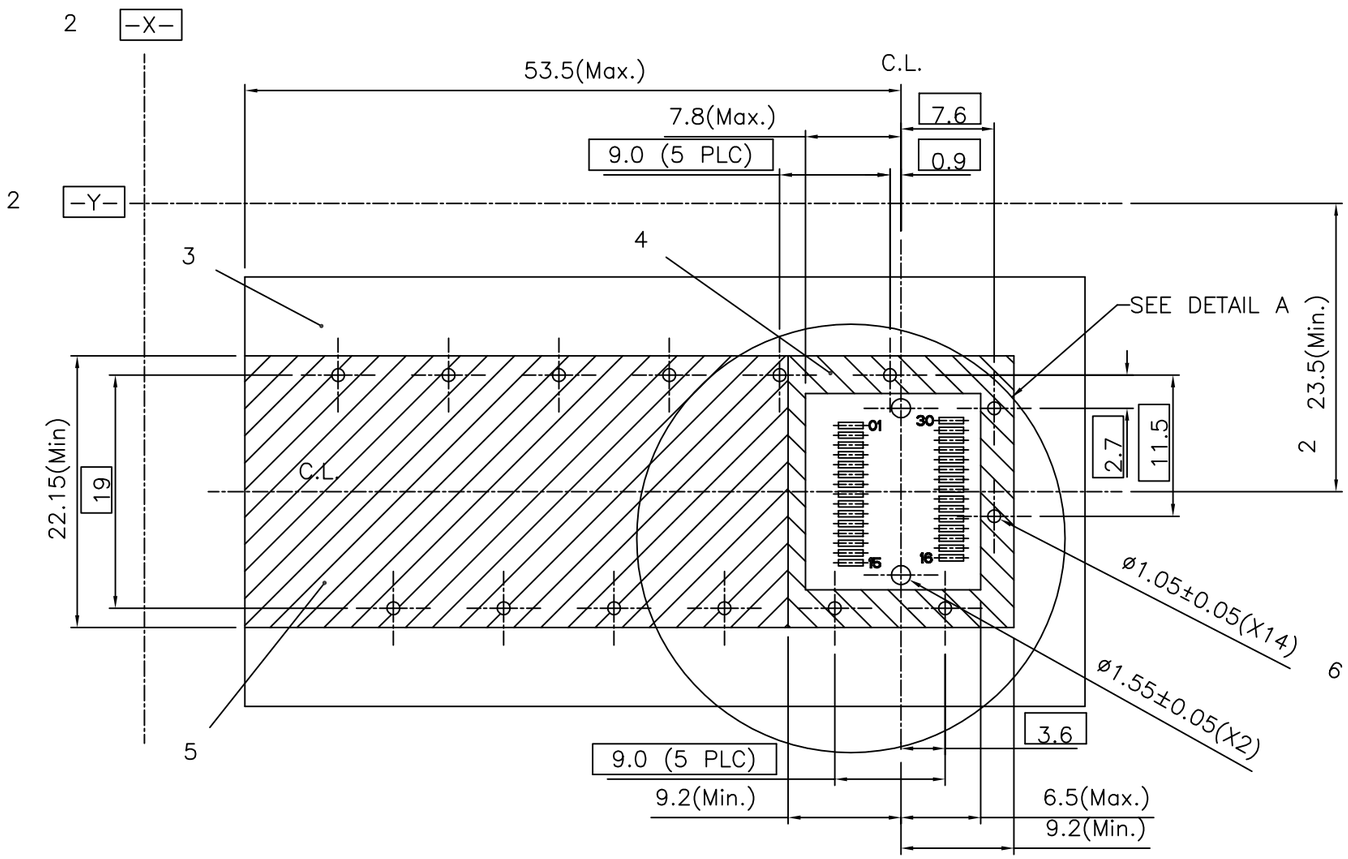
DRAWING NO. XFP003-L	SIZE	REV
/PART NO. SEE NOTE	A3	0
DO NOT SCALE DRAWING	SHEET 1 OF 2	

H G F E D C B A

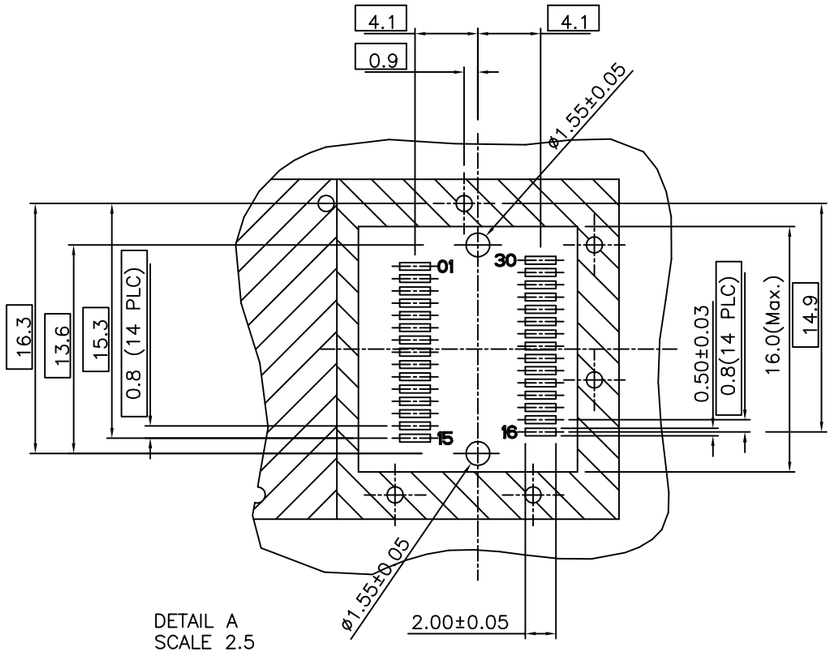
8 7 6 5 4 3 2 1

A1RFRD10

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



RECOMMEND P.C.B. LAYOUT



DETAIL A
SCALE 2.5

Note:

1 DESIGN MEETS REQUIREMENTS OF XFPMSA SPECIFICATION REV. 3.1 (10 GIGABIT SMALL FROM FACTOR PLUGGABLE MODULE).

2 DATUM -X- AND -Y- ESTABLISHED BY CUSTOMER.

3 DATUM -A- IS TOP SURFACE OF HOST BOARD.

4 INDICATED SURFACES TO BE CONDUCTIVE AND CONNECTED TO CHASSIS GROUND.

5 CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

6 RECOMMENDATION FOR P.C.BOARD HOLES:
A. HOLE ø AFTER DRILLING : 1.15±0.02 mm.
B. HOLE ø Sn PLATE : 1.05±0.05 mm.
C. 25um ~ 50um COPPER UNDERPLATE.

7 -CAUTION- REFLOW PROCESS WILL DAMAGE CAGE ASSEMBLY.

DETACHED LISTS

MM (INCH)
TOLERANCES EXCEPT AS NOTED
MM
.0 ± 0.2 ±
.00 ± 0.15 ±
.000 ± 0.075 ±
ANGLES ± 0.5
THIRD ANGLE PROJECTION

DFTO tzou	DATE 06/02/06'
CHKD	DATE
MFO	DATE
APPVL	DATE
MATERIAL :	
QT'Y :	
FINISH :	
SCALE : 1 : 2	

FULL RISE ELECTRONIC CO., LTD

TITLE (Non-Logo)
XFP CAGE WITH PCI HEAT SINK KIT

DRAWING NO. XFP003-L	SIZE A3	REV 0
/PART NO. SEE NOTE		
DO NOT SCALE DRAWING	SHEET 2 OF 2	

8 7 6 5 4 3 2 1

H G F E D C B A